Thin glass substrates for microelectronic and photonic applications
Flat, smooth, and extremely **thin glass** is available in the market

Handling in automated lab equipment is a challenge
Mosaic creates a **robust wafer handling solution**

Thin bare glass, or with through-holes
- Flatness is a challenge

**Mosaic product:**
Thin bare glass or with through-holes temporarily bonded to a glass or silicon carrier wafer
- Addresses flatness
- Equipment interface is Si wafer

**Can be processed like a standard silicon wafer**
Mosaic proprietary bond material is key

- Bond is temporary to $\geq 450^\circ$ C
- $\ll 1$ um thick layer
- No outgassing during vacuum processes
- Compatible with silicon processing (installed equipment base)

Mechanical debond ("peel") with low force
Mosaic Microsystems Summary

- Industry trends require new packaging solutions
- Glass is an attractive solution for several industry needs but gaps in the supply chain has made adoption difficult

Mosaic Microsystems provides solutions to enable cost-effective manufacture for glass/TGV and other thin substrates in high volume environment
Thank you